

Advanced technologies providing RF capabilities for satellite systems

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Agenda

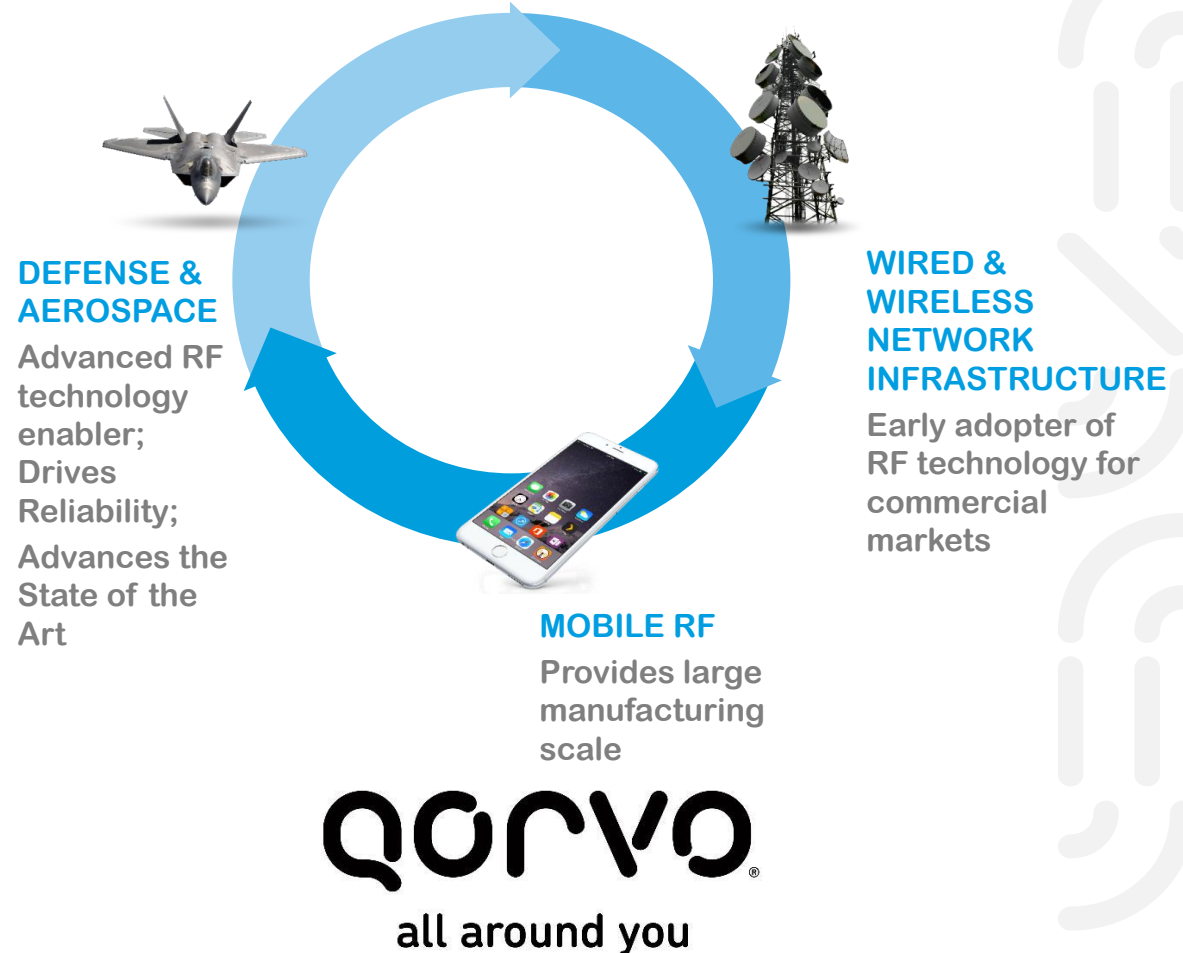
- Qorvo Space Business Approach
- “Typical” Space Flow Chart
- Qorvo GaN Process Qualification
- Product/Design Enhancements



What is Qorvo doing for Space Applications?

Innovative RF solutions for everything that connects our world

- We provide innovative RF solutions
- 25+ years of Space Qualification Heritage
- Committee participant in industry led GaN for Space consortium
- Space Qualification at the die level
- Tailor the qualification to the customer needs
- In house commercial grade packaging
- GaAs and GaN qualified processes.



Qorvo's Space Strategy

Build on Qorvo's +25 year space qualified GaAs MMIC legacy

Offer space products and services that support our customers

Continue to support legacy products and programs



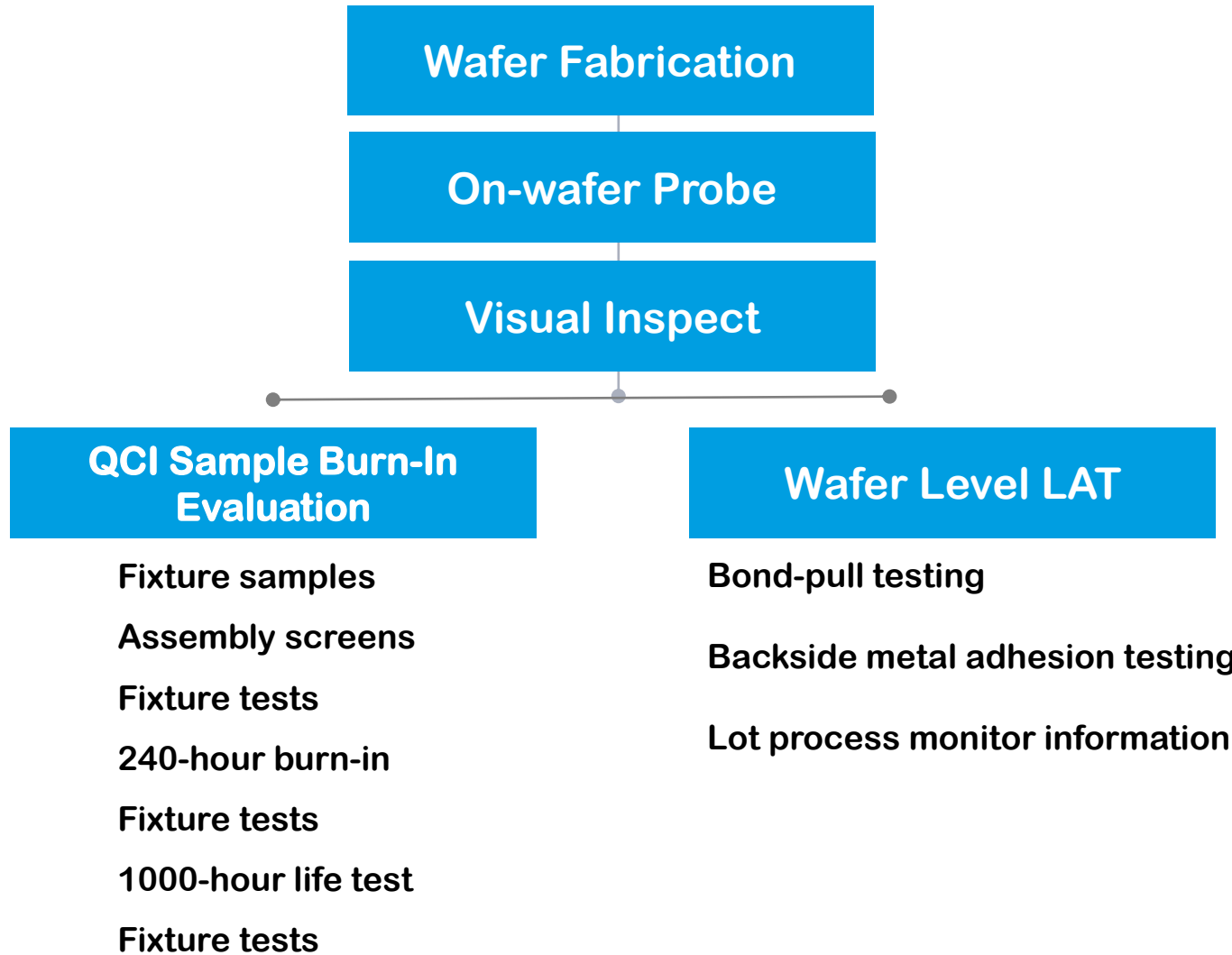
Push GaN space qualification capability

Active participation in GaN space qualification roundtables

Qorvo GaAs pHEMT processes, QGaN15 & QGaN25 are released processes for Space applications



A “Typical” Space Qualification Flow Chart



Other Capabilities

- Visual Inspection options
- Commercial Packaging
- In house Assembly
- Design Partnering
- 3rd Party sourcing for additional testing

Customizable for specific opportunity needs



Qorvo 250nm and 150nm GaN Process Qualification

Stress Testing

Accelerated Life Testing

Extended Reverse Bias Test

Gain Stability

Power Step Stress

Early Life Failure Test

ESD (HBM, CDM)

Hydrogen Sensitivity Test

Life Testing

DC Accelerated Life Testing

RF Operating Life Testing

RFOLT QGaN25*

Pulsed RFOLT QGaN25*

Radiation Hardness

Total Ionizing Dose

Total Ionizing Dose Testing

Proton Radiation Testing

Heavy Ion Testing (SEE)

- Completed testing by Qorvo or one of Qorvo's Partners
- In the absence of an industry wide standard, Qorvo has used these successful tests as the basis for space qualified process declaration.



Performance Enhancements



Performance (SWaP-C)

- Frequency
 - Product development for traditional and emerging satellite bands - **Specific bands versus wideband**
 - Reconfigurable MMICs Capability – **Size & component count reduction; Performance boost over wideband**
- Power Added Efficiency – **Simplify Thermal Management; Extend Battery Life**
 - Process enhancements – **Loss reduction; Reducing power dissipation**
 - Design for Max PAE - **Load Targets, Doherty, Bias Class, Harmonic Trapping**
 - **New design techniques** enabled by process enhancements
- Linearity – **Reduce Distortion; Reduce data errors**
 - **Clear requirement definition at the component level** not just the system level requirement
 - **Design with linearity as a priority** versus saturated power and bandwidth
 - **FET model optimized for linearity**
 - Data collection and application circuit optimization
- Thermal Dissipation
 - **Accurate Finite Element Models for Channel Temperature** that are validated with Micro Ramen measurements
 - In-house & high volume eutectic die attach for GaAs and GaN to a variety of heat spreader material types
 - FET layout with RF and thermal performance considerations



SWaP-C: Size, Weight and Power & Cost

Provides clear advantages

Size & weight

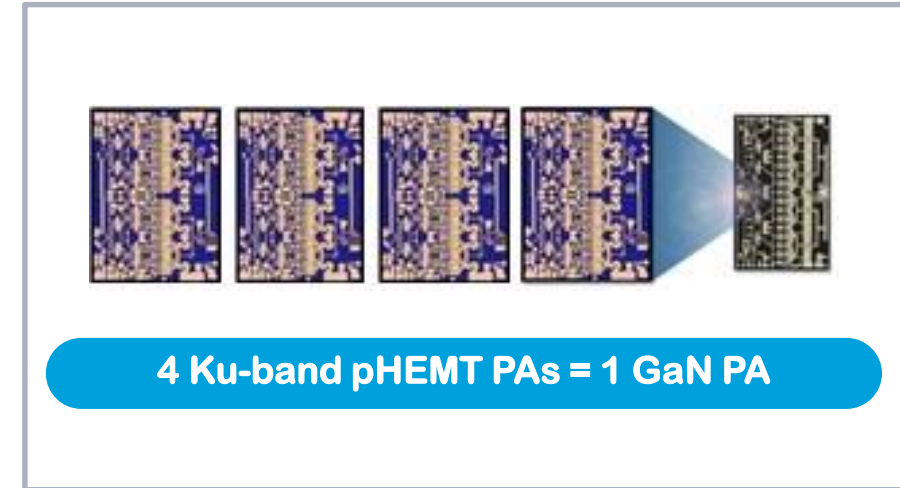
- Critical in Space applications
- GaN offers a 3-5X increase in power density versus GaAs
- Packaging for Commercial (LEO or Short Operating Life)

Power

- LNA power consumption must be evaluated
- Higher power-added-efficiency (PAE) = less system prime power
- Higher operating voltage = less current and lower I^2R loss

Cost

- Lower system level operating cost
- Higher W/mm = smaller size = lower weight



Manufacturing Options for SWaP-C

High K materials for increased thermal dissipation (weight & power)

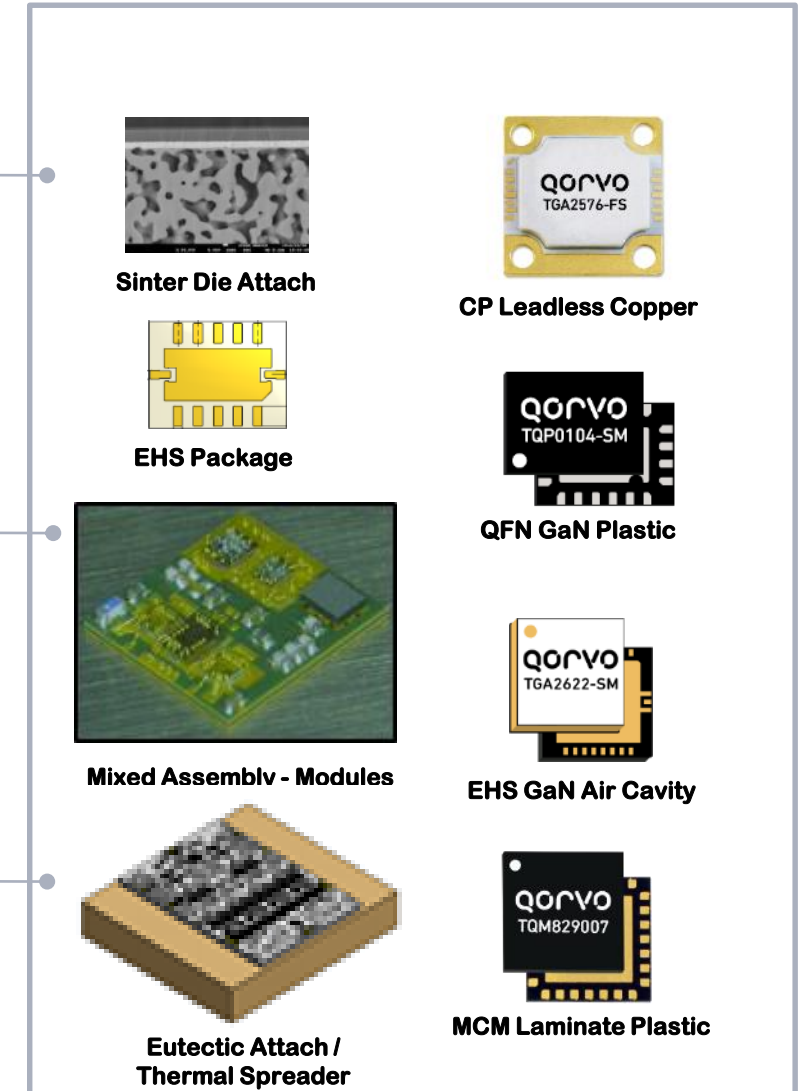
- Direct Cu attach vs. CuMoly or CuW composites for the highest K
- High K die attach materials

Packages (size, weight and power)

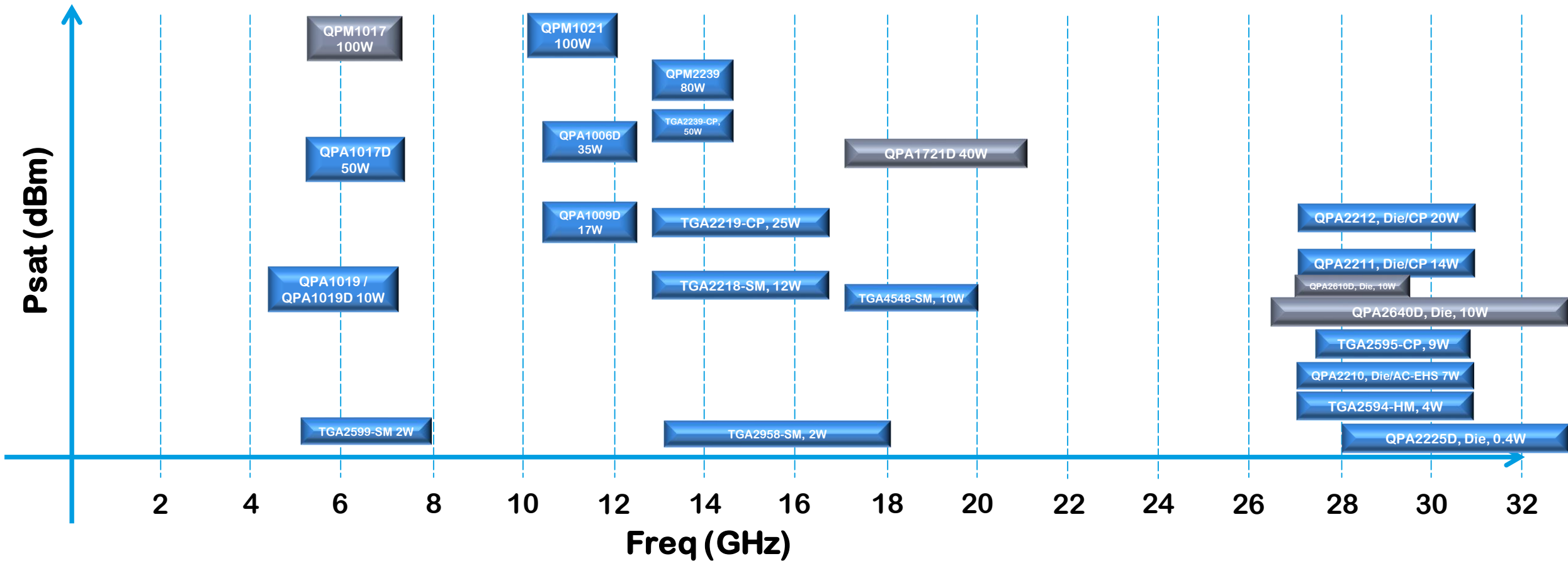
- Thermal Spreader Direct Attach
- Embedded heat sinks or Cu bases

Assembly for size and Weight reduction

- Bump die or flip-chip
- Die to die bonding



Frequency Coverage Highlights for GaN MMIC PAs



GaAs LNAs and RF control integrated circuits also available.



S/X band Reconfigurable 25W GaN HPA

Peak Performance in bands; Size & Weight reduction

Advantages over Broadband Amp?

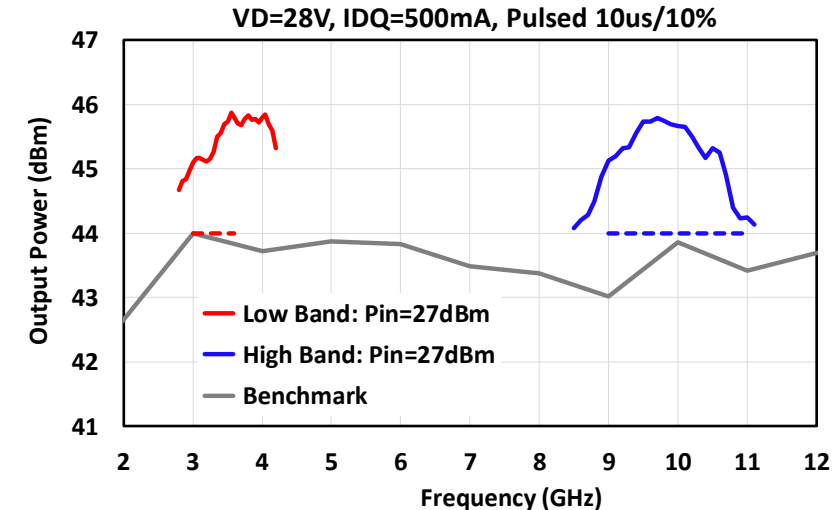
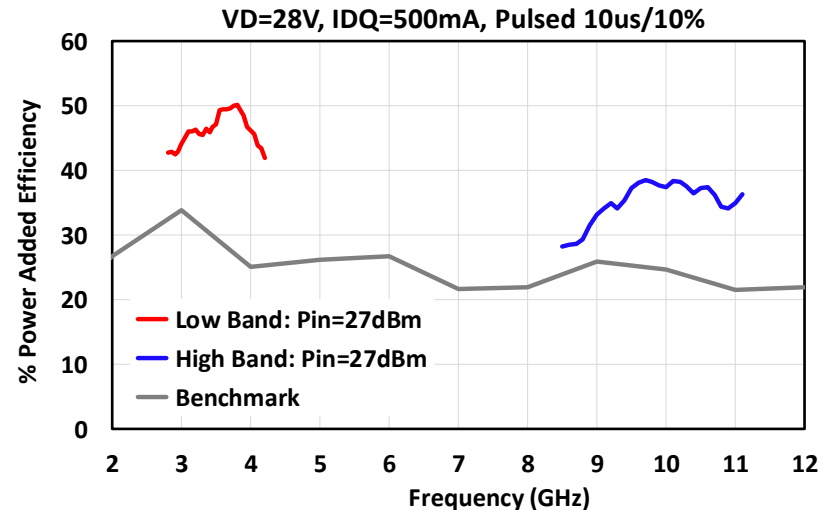
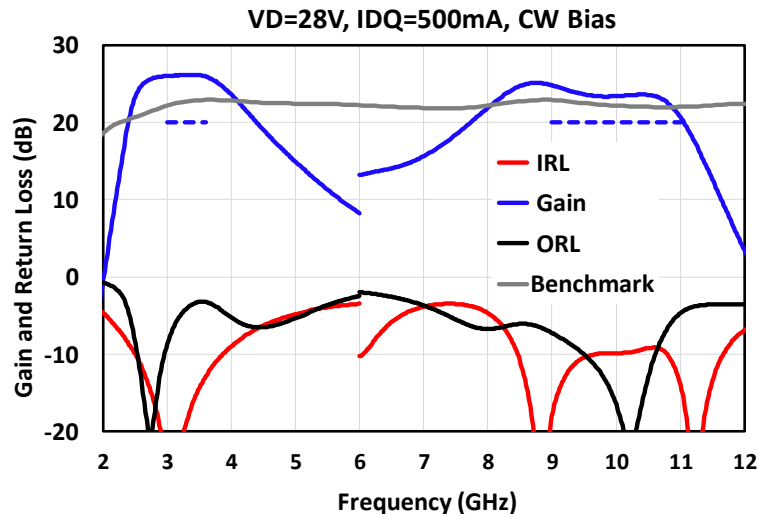
- 25% Less Die Area
- More S-band and X-band Gain
 - Power Up: 1.1-2.1 dB
 - PAE up 10-20 points
- X-Band Operation
 - Power Up: 0.7-2.1 dB
 - PAE Up: 8 to 15 point

2-18 Ghz 20 W NDPA Die Size:
5.34 (X) x 5.00 (Y) = 26.7 mm²



Performance

- S-band 3.0-3.5 GHz
 - Power: 32-38 W
 - PAE: 44-47 %
- X-Band 9-11 GHz
 - Power: 26-37 W
 - PAE: 33 38%
- Die Size: 5.1 x 3.92 = 20 mm²



Power Amplifier Classes

Power Amplifier Class	Max Theoretical Drain Efficiency	Conduction Angle	Advantages	Disadvantages
A	25%-50%	$\Theta = 360$	Can be simpler than other classes, amplifying element is always conducting Device has no “turn-on” time, typically better higher frequency performance	Low efficiency, More heat dissipation, stresses power supply.
AB	50 - 78.5%	$180 < \Theta < 360$	Higher efficiency than Class A, Better linearity than Class B, Higher ss gain; Higher RF Power	Lower Efficiency than Class-E/F
B	78.5%	$\Theta = 180$	Better possible efficiency versus Class AB and A	Crossover distortion; degraded linearity
C	80%	$\Theta < 180$	High efficiency	Degraded linearity
E	100%	$\Theta = 0$	Higher efficiency	Degraded linearity; Very low ss gain; BW limited due to harmonics; Large voltage swing across the device; Requires higher voltage handling for the transistors and capacitors; Can be difficult to match
F	100%	$\Theta = 0$	Higher efficiency	Degraded linearity; Very low ss gain; BW limited due to harmonics; Requires higher voltage handling for the transistor and capacitors; Output capacitance of device not naturally absorbed into network → need inductor to tune it out



Power Added Efficiency

X-band & S-Band Examples; Applicable to Satellite bands; Linearity must be evaluated

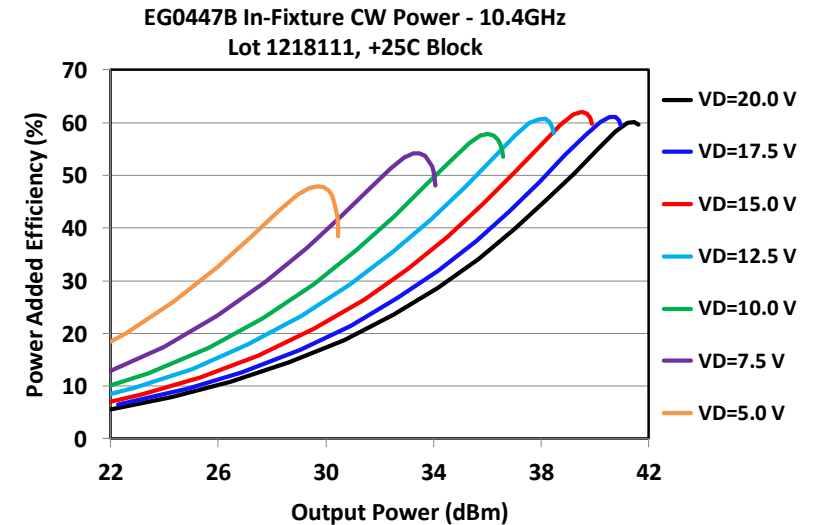
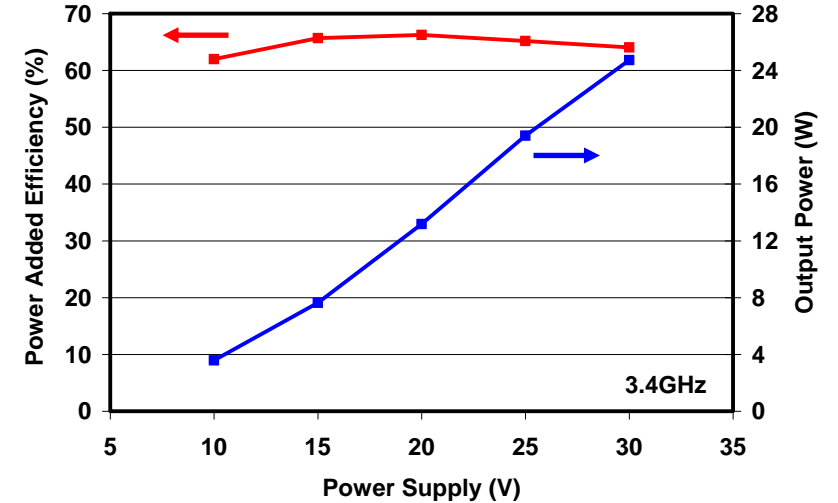
- High efficiency switched mode of operation
- Bandwidth requirements are modest
- Theoretically maintains PAE at reduced power supply voltage
- Theoretically linear output power in Watts versus supply voltage
- Simple low loss output matching network (~ 0.4dB)



S-band; 20W (CW), 60% PAE, 33dB Gain



X-band Class-E: 13W (CW), 60% PAE, 20dB Gain



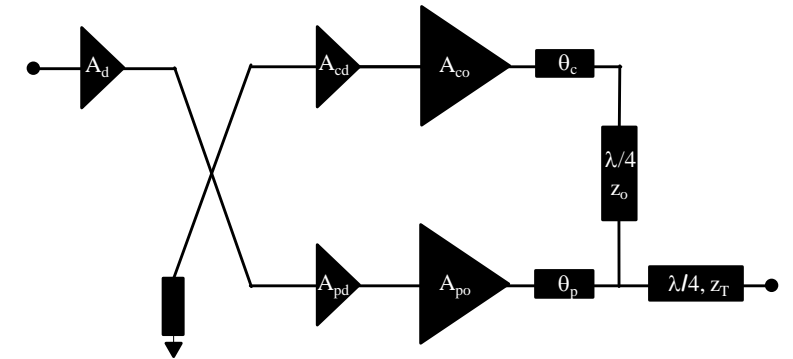
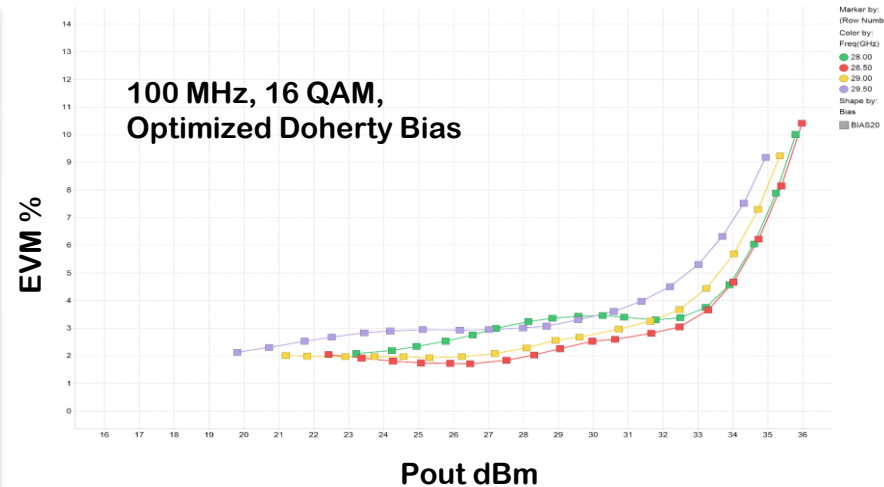
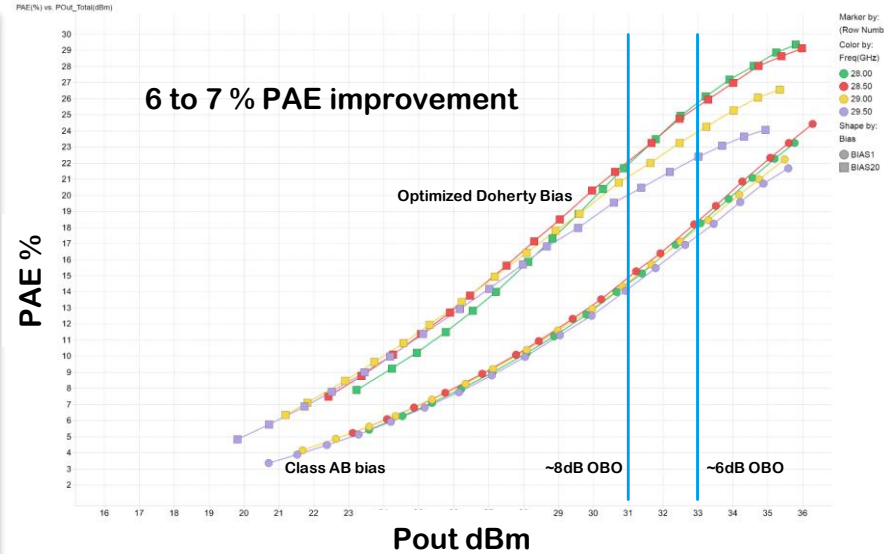
10W Psat Ka-band Doherty

QPA2810

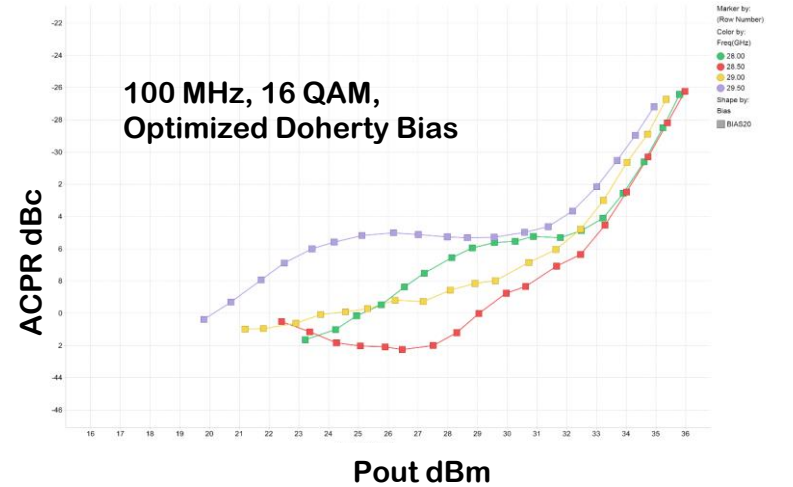
Freq: 27 to 29.5 GHz
 Psat: 40 dBm
 At 8 dB OBO:
 Power: 31.5 dBm
 PAE: >20%
 Gain: 26dB
 Bias:
 Technology: QGaN15
 Package: die
 Size: 4.22 x 2.30 x 0.1mm

Benefits

High PAE in back-off power conditions compared to Class AB bias
 EVM and ACPR improvements compared to Class AB bias



QPA2810D Block Diagram



X-band: 10.7-12.7GHz 35W & 17 W GaN PAs

QPA1006D

Bias: 20V/1200mA
 IM3: 26dBc, P0=38dBm/tone
 Size: ~25.9mm²

QPA1009D

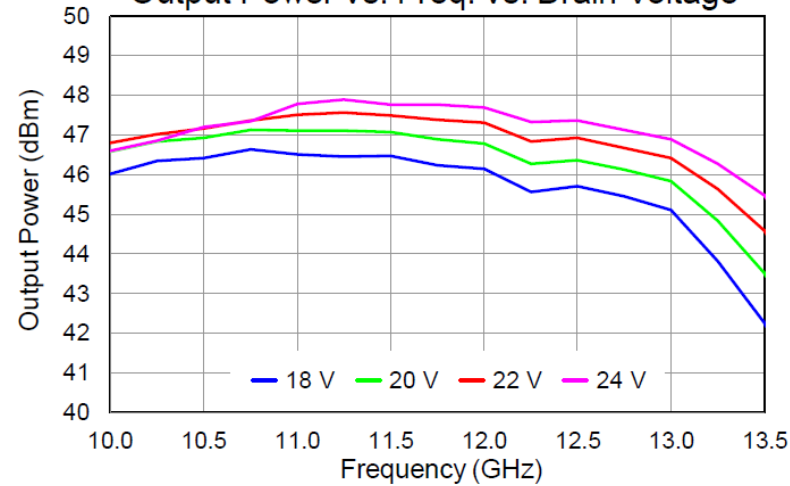
Bias: 22V/380mA
 IM3: 33dBc, P0=35dBm/tone
 Size: ~13.5mm²

Power, Efficiency & Linearity
 for SATCOM.

SWAP-C being applied at the
 IC design level.

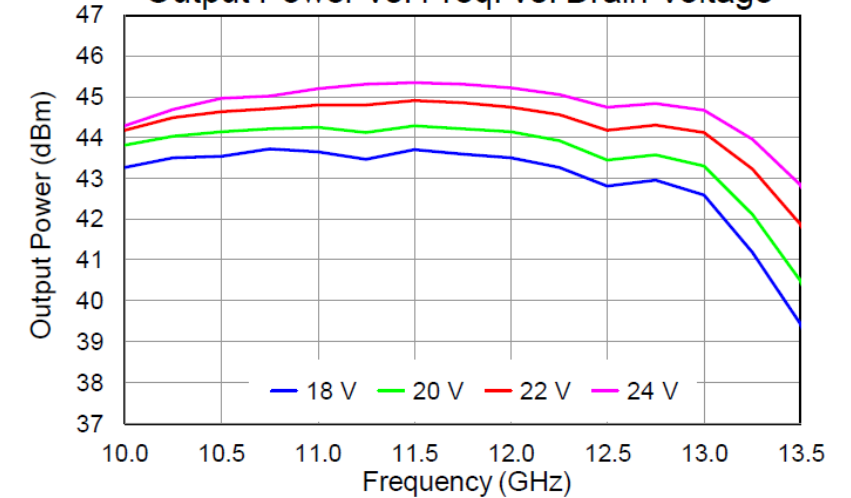
QPA1006D

Output Power vs. Freq. vs. Drain Voltage

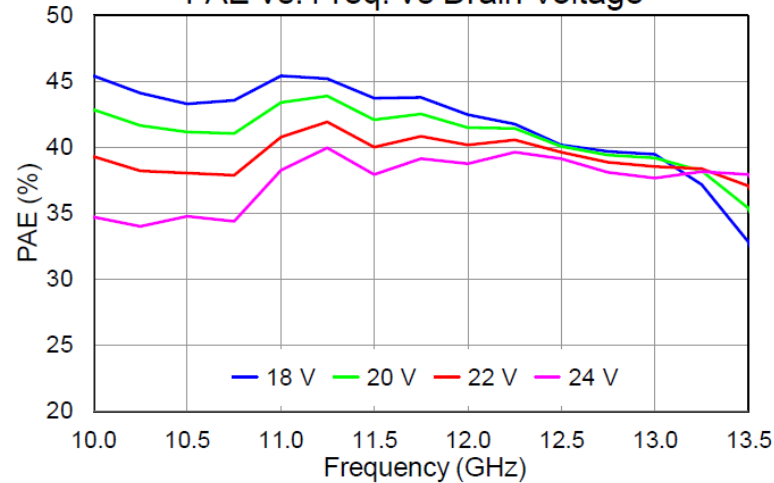


QPA1009D

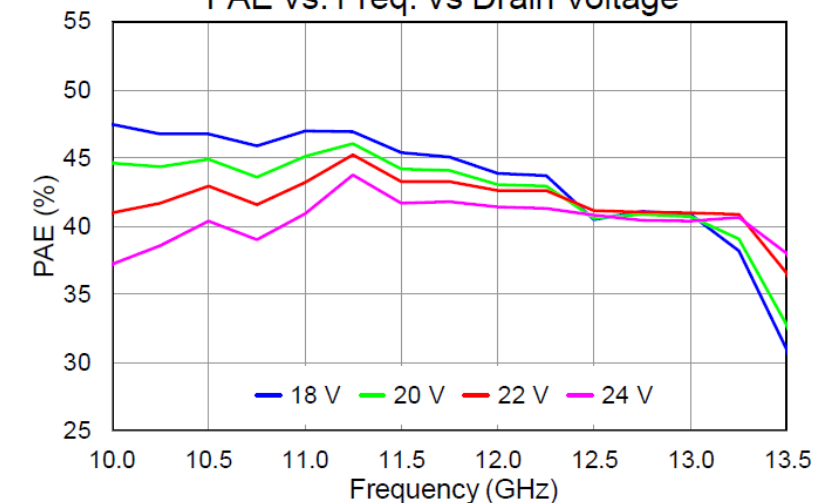
Output Power vs. Freq. vs. Drain Voltage



PAE vs. Freq. vs Drain Voltage



PAE vs. Freq. vs Drain Voltage



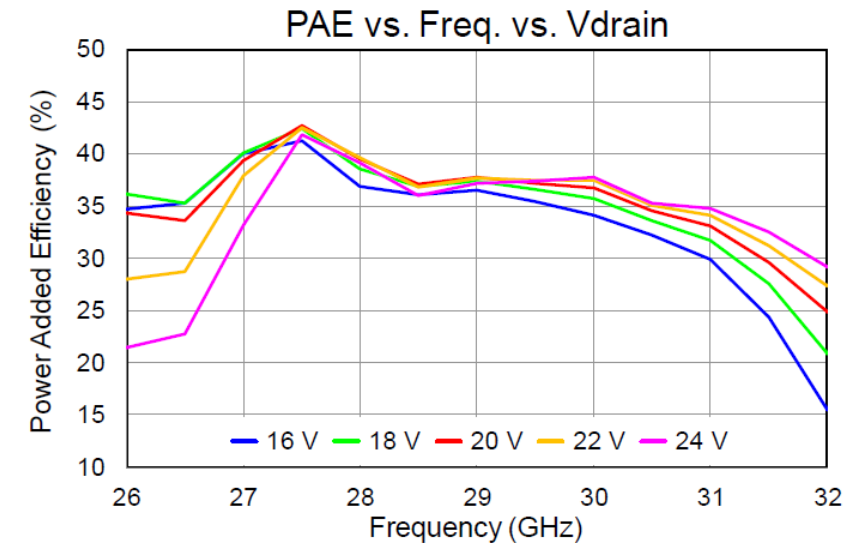
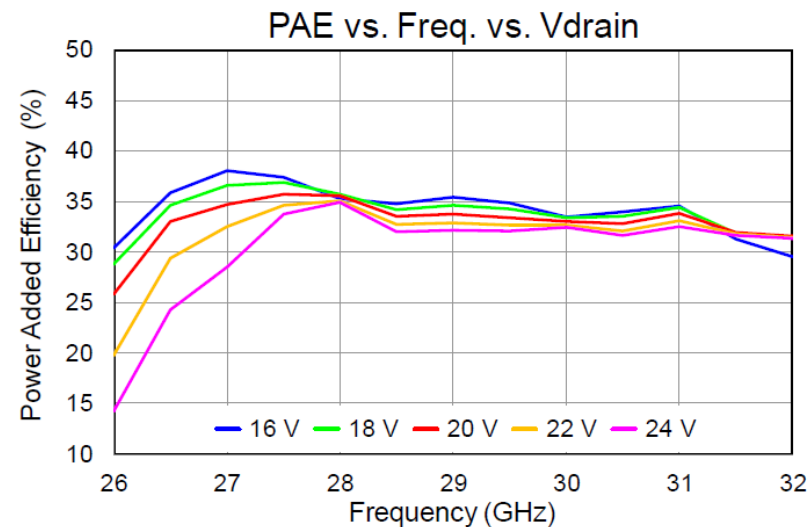
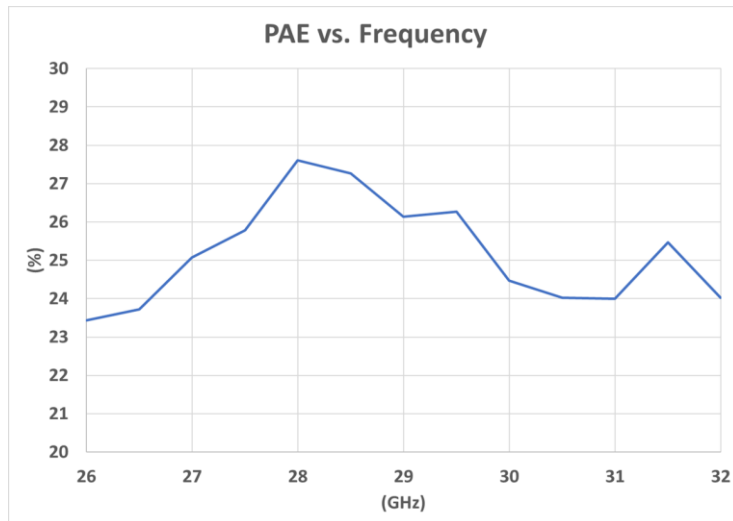
Ka-band: Linear Power and Efficiency for Satcom

Model & Design for Linearity/PAE/Size - Directly Impacts the System SWAP

Psat: 20W
PAE: 26%
LSG: 18dB
IMD3: 5W/tone, 25dBc
SSG: 23dB
Bias: 20V/560mA
Technology: QGaN15ES

Psat: 7W
PAE: 32%
LSG: 16dB
IMD3: 1.25W/tone, 25dBc
SSG: 25dB
Bias: 20V/200mA
Technology: QGaN15ES

Psat: 14W
PAE: 34%
LSG: 17dB
IMD3: 2.5W/tone, 25dBc
SSG: 26dB
Bias: 22V/280mA
Technology: QGaN15ES





Thank You